

## ABSTRACT

Processes and device structures for constructing RFID tag and smart card and toy controller integrated circuit transceivers built inexpensively using flat panel display manufacturing machines on large plastic or glass or plastic laminated to glass substrates using thin film technologies at low temperatures and using chemicals and gases which will not attack or damage the substrate. Also disclosed are structures to eliminate the reliability problems caused by differential strain caused by different coefficients of thermal expansion.

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Ronald C. Fink